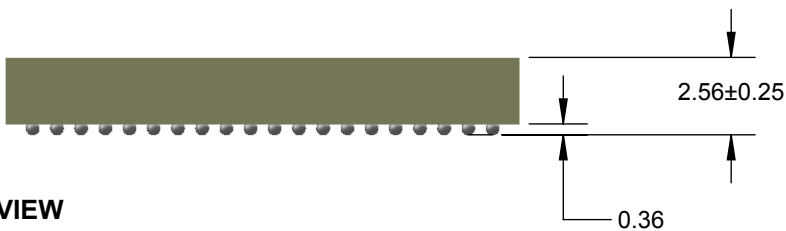
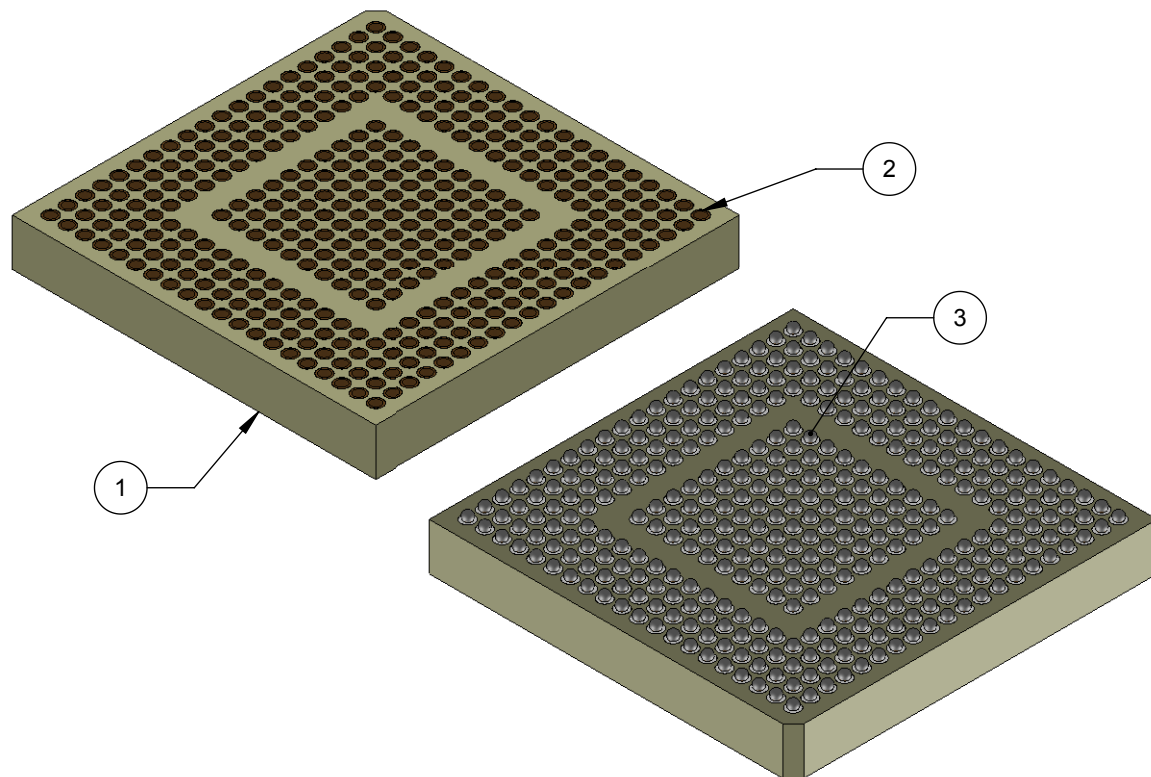


TOP VIEW




FRONT VIEW

Item No.	Description	Material
1	Substrate	High Temp FR4
2	0.75mm Giga-snaP Receptacle	Shell: Brass Alloy 360; 0.25µm [10µ"] Au over 2.54 µm [100µ"] Ni finish Contact: BeCu Alloy 172; 0.25µm [10µ"] Au over 1.27 µm [50µ"] Ni finish
3	Solder ball	Sn96.5Ag3.0Cu0.5

Description: Giga-snaP BGA SMT Foot

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 SF-BGA356C-B-64F Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Material: N/A Finish: N/A Weight: N/A	STATUS: Approval Pending	SHEET: 1 OF 1	REV. -.01
		ENG: M.A. Fedde	DRAWN BY: M. Raske	SCALE: 4:1
		FILE: SF-BGA356C-B-64F Dwg	DATE: 03/26/2014	